Poster Presenttion: Nov. 4, 2021 (Thu.) 2:40~3:20 P.M.

Room Forum 2, 3F

Session Chair: Young-Bae Park (Andong National University/ Korea)

No	Topic	Author	Affillition	Country	Paper Title
P1-01	Microelectronics & Packaging Materials	MiKyeong Choi*,**, DongSu Ryu*, DongJoo Park*, JinYoung Khim*, SeungBoo Jung†**	Amkor technology korea*, Sungkyunkwan University**	kr	Advanced Thermal Interfacial Material with High Thermal Conductivity for Thermal Packaging Challenges
P1-02		Yongchan Kwon, Jung Won Kim, Tae Hoon Kim, Seong Won Seo, Jung-Rae Park, Cheong-Ha Jung, Gu-Sung Kim†	Kangnam University	kr	A Study on the Major Characteristic Factors of Oxide Dielectric
P1-03		Seong-Gyu Ko, Nakyung Oh, Chan-Ho Jeon, Sang-Gyu Choi, Hyeon-Woo Son, Sang-Wook Kim, Soong-Keun Hyun†	Inha University	kr	Characterization of Joining Properties of Ni-coated Cu/MnSi Joint Brazed by Ag-Cu-Zn-Sn Filler Metal
P1-04		Eun Ha, Haksan Jeong, Seungboo Jung†	Sungkyunkwan University	kr	Effect of EMI Shielding Fillers in EMC on RF Characterization in Range of 18GHz for Fan-out Package Structure
P1-05		Alexsandro Bobsin, Tayná Copes Rodrigues, Paola Lamberty, Iara Fernandes, Sandro Binsfeld Ferreira, Celso Peter, William Dutra, Willyan Hasenkamp†*, Carlos Alberto Mendes Moraes	Universidade do Vale do Rio dos Sinos (UNISINOS), HT Micron*	br	Conductive Films Produced by Ag and Core-shell (cu@Ag) Inks for Electromagnetic Shielding in Accordance with ASTM D4935
P1-06		Iara J. Fernandes, Tayná Copes Rodrigues, Paola Lamberty, Alexsandro Bobsin*, Celso Peter, Willyan Hasenkamp**, Carlos Alberto Mendes Moraes*	Universidade do Vale do Rio dos Sinos (UNISINOS), Universidade do Vale do Rio do Sinos*, Hana Micron Co., Ltd.**	br	Application of Silver Nanoparticle Inks for the Production of Films in Conformal Shielding on SiP
P1-07		Jun-Ho Jang, Haksan Jeong, Dong-Gil Kang, Kyung Deuk Min, Ji-Won Baek, Seong-Boo Jung†	Sungkyunkwan University	kr	Drop Properties of Wafer Level Package Modules with Various Underfill Materials
P1-08		DongGil Kang, HakSan Jung, KyungDeuk Min, JunHo Jang, Eun Ha, JiWon Baek*, SeungBoo Jung†	Sungkyunkwan University, Wonchemical*	kr	Evaluation of Bending Characteristics of WLP Module with Three Types of Underfill
P1-09		Jiyong Yim, Rino Choi†, Daewoong Kwon	Inha University	kr	$HfZrO_2$ Based Ferroelectric-gated IGZO Thin Film Transistor Memory
P1-10		Jeong-han Kim, Rino Choi†, Daewoong Kwon	Inha University	kr	$HfZrO_2$ Ferroelectric Tunneling Junction with IGZO Insertion for Unidirectional Self-rectifying Characteristics
P1-11		Jinshu Li, Qi Zhang†, Euy Heon Hwang	Sungkyunkwan University	kr	Hot Electron Relaxation in MoS_2 and WSe_2 Field-effect Transistors
P1-12		Hyunseong Shin†, Haolin Wang	Inha University	kr	Multiscale Model to Predict Fatigue Crack Propagation Behavior of Epoxy Nanocomposites
P1-13		Hyo Eun Kim, Jun Seong Ji, Ye Ji Kim, Han Gyoel Jeon, Eun Sol Jo, Gu Sung Kim†	Kangnam University	kr	A Study on the Electrical Characteristic by Interposer Materials
P1-14		Harshada Patil, Honggyun Kim, Shania Rehman, Kalyani D. Kadam, Jamal Aziz, Muhammad Farooq Khan, Deok-kee Kim†	Sejong University	in	Inorganic Protection Layer for Stable Resistive Switching of Organic Bulk Heterojunction
P1-15	Packaging Processing & Equipment	Deokjin Seo, Ryu Jongin†	Korea Electronics Technology Institute	kr	Implementation of Magneto-Electric Dipole Antenna with Dual Polarization Using LTCC Process
P1-16		Jong-Min Yook†, Hyun Je Chang, Jiyeon Park, Dongsu Kim	Korea Electronics Technology Institute	kr	Through-hole Silicon Capacitor for 3D-IC Package
P1-17		Jae Woo Song, Sun Kook Kim, Se Hoon Park†	Korea Electronics Technology Institute	kr	Driver Amplifier Module with Face Up Fan-out Packaging Structure Using Thermosetting Low Loss Material Applicable to mmWave
P1-18		Dong Hyeok Bae, Se-Hoon Park†	Korea Electronics Technology Institute	kr	Plasma Treatment for Fan-Out Packaging Low Loss Dielectric Layer
P1-19		HyeokJin Chu, Sungdong Kim†	Seoul National University of Science and Technology	kr	Implementation of Multi-RDL Layers Using Polymeric ILD for FOWLP
P1-20		Jein Yu†, Dongsu Kim, Jong-Min Yook	Korea Electronics Technology Institute	kr	Substrate-embedded Ferrite Core Inductorusing Photosensitive Glass Substrate for Integrated Voltage Regulators
P1-21		Ju Seung Lee, Tae-il Kim†	Sungkyunkwan University	kr	Nanoscale Dewetting Based Direct Interconnnection System for Assembly of Microscale Electronics
P1-22		Mingyu Kim, Rino Choi†	Inha university	kr	High Precision Hybrid Bonding Alignment System with Visible Laser
P1-23	Flexible, Wearable, & Printed Electronics	Xuan Luc Le, Duc Thinh Vuong, Sung-Hoon Choa†	Seoul National University of Science and Technology	kr	Improvement of Reliability and Flexibility for Flexible Solar Cell with Filled Structure and Optical Adhesive
P1-24		Hyun Jin Nam, Se-Hoon Park†	Korea Electronics Technology Institute	kr	Development and Characteristics of Multipurpose Transparent Polyurethane Film
P1-25		Hyun Jin Nam, Wal young Kim*, Na Young Seo*, Su-Yong Nam*, Se-Hoon Park†	Korea Electronics Technology Institute, Pukyong National University*	kr	Development of Stretchable Electrodes for Wearables Using Vacuum Thermal Pressure
P1-26		Chanho Jeong, Tae-il Kim†	Sungkyunkwan University	kr	Spatial Independent Zone for Dynamic Noise Unaffected 2D Sensors
P1-27		Jehoon Lee, Jongkyu Won, Jungwon Kang†	Dankook University	kr	Characteristics of The Colorless Polyimide-Based Flexible X-ray Detector with Non-Fullerene Polymer
P1-28		Young Jin Jo, Tae-il Kim†	Sungkyunkwan University	kr	Organic Transistors Based on Biocompatible and Biodegradable Solid-state Electrolyte
P1-29		Jiyoon Youm, Seung-Hwan Lee, Inhee Cho, Da-Woon Jeong, Hyung-Ho Park*, Min-Su Kim†	Korea Institute of Industrial Technology, Yonsei University*	kr	Optimization of Carbon Solution for Fabrication of Conductive Cellulose Nanofiber Column of Electrokinetic Power Generator
P1-30		Kalyani D. Kadam, Honggyun Kim, Shania Rehman, Harshada Patil, Jamal Aziz, Tukaram D. Dongale, Muhammad Farooq Khan, Deok-kee Kim†	Sejong University	in	Modification in Electron Transport Layer for Efficient Flexible Organic Solar Cells
P1-31		Seung-hyun Oh, Sol-Kyu Lee, Young-Woon Cho, Seung-Kyun Kang†, Sang-Bum Kim†, Young-Chang Joo†	Seoul National University	kr	Nanofiber Channel Organic Electrochemical Transistors for Low-Power Neuromorphic Computing and Wide-Bandwidth Sensing Platforms

No	Topic	Author	Affiliation	Country	Paper Title
P1-32		Gyeongyeong Cheon, Jahyeon Kim, Byeongjin Ahn, Min-Su Kim, Junghwan Bang, Young-Bae Park, Yong-Ho Ko†	Korea Institute of Industrial Technology	kr	Bonding Properties of a Low-temperature Solder on Polymer-based Substrates by Laser Bonding Processes
P1-33		Byungwoo Kim, Yoonchul Sohn†	Chosun University	kr	A Study on the Reaction between Liquid Ga and Pd Substrate for the Application of Flexible Electronic Devices
P1-34		Hyeokgi Choi, Yoonchul Sohn†	Chosun University	kr	A Study on the Reaction between Liquid Ga and Au Substrate for the Application of Flexible Electronic Devices
P1-35	Sensors, LED, & MEMS/NEMS Packaging Technology	In-Seok Kye, Yong-Sung Eom†, Jiho Joo, Gwang-Mun Choi, Ki-Seok Jang, Chanmi Lee, Yong-Jun Oh, Kwang-Seong Choi	Electronics and Telecommunications Research Institute	kr	Microstructure Analysis of Mini LED Bonding Joint Transferred and Bonded Using the Simultaneous Transfer and Bonding (SITRAB) Process
P1-36		Injoo Kim, Sungdong Kim†	Seoul University of Science and Technology	kr	Development of a Vacuum Device for Micro LED Transfer
P1-38		Ko DeaHyeon, Kim Minju, So Younghee, Sungwook Mhin†	Kyonggi University	kr	One Step Solid State Reaction of $(Ni,Co,Mn)O_4$ Pellet as Negative Temperature Coefficient Sensor
P1-39		Myounghun Kim, Kwang-Seok Kim†	Korea Institute of Industrial Technology	kr	Fabrication of Cu-Graphite Composite Sheets for Electromagnetic Wave Shielding and Heat Dissipation Using Direct Coating and Atmospheric-Pressure Plasma Annealing
P1-40		Doa Kim, Doo in Kim, Myung Yung Jeong†	Pusan National University	kr	Hardness Enhancement on Superhydrophobic Surface for Electronic Packaging
P1-41		Bong-Gyu Bae, Hyewon Park, Young-Jun Lee†, Joo-Hyung Kim	Inha University	kr	Performance Comparison of SAW Sensor by Coating Methods for the Detection of Chemical Warfare Agent Simulants
P1-42		Kwanyong Lee, Jehoon Lee, Mr. Daeho Han, Jungwon Kang†	Dankook University	kr	A Study of Improving the Sensitivity of Indirect X-ray Detectors by Adding Hybrid Perovskite Quantum Dots
P1-43		Xuan Luc Le, Duc Thinh Vuong, Sung-Hoon Choa†	Seoul National University of Science and Technology	kr	Lifespan Prediction and Durability of MEMS Vertical Probe Using Various Interconnection Structures
P1-44		Duc Thinh Vuong, Xuan Luc Le, Sung-Hoon Choa†	Seoul National University of Science and Technology	kr	Modelling of Peeling Process of Adhesive Tape for Electromagnetic Interference Shielding
P1-45		YeongJun Park, Kwangsik Oh, Seungmin Park, YoonHo Kim, Sarrah Eun Kyung Kim†	Seoul National University of Science and Technology	kr	Highly Selective Cu Etching in Cu/Ni Layer Structures for Probe Pin Fabrication
P1-46		Jong Uk Kim, Seok Joon Kwon, Tae-il Kim†	Sungkyunkwan University	kr	Broadband Light Absorber with Hierarchical Nanoturf structures for Solar-Thermal Applications
P1-47		Hyeonjung Yang, Semi Jeong, Hyouk Lee†*	Korea University of Technology and Education, Flexscom*	kr	Development of Flexible Semiconductor Products Using Roll Transfer Equipment
P1-48		Ms. Sang-Kwon Kim, Prof. Ji-Wook Yoon†	Jeonbuk National University	kr	Facile Fabrication of Porous CuBr Films by a Solution Oxidation Method at Room Temperature

Room Forum 3, 3F

Session Chair: Yong-Ho Ko (Korea Institute of Industrial Technology)

No	Topic	Author	Affiliation	Country	Paper Title
P2-01	Interconnection	Lee Wan Geun, Jong-Hyun Lee†	Seoul National University of Science and Technology	kr	Formation of Nano-Porous Structured Cu by Selective Corrosion of Brass Alloy and Sinter Bonding for Cu-Cu Direct Bonding
P2-02		Jia-Juen Ong, Kai-Cheng Shie, Chih Chen†	National Yang Ming Chiao Tung University	tw	Microstructure Analysis and Thermal Fatigue Enhancement in Cu-Cu Joints
P2-03		YoonHo Kim, SeungMin Park, Sarrah Eunkyung Kim†	Seoul National University of Science and Technology	kr	Low Teperature Cu-Cu Bonding Using Ag Nanolayer
P2-04		Seungmin Park, YoonHo Kim, YeongJun Park, Sarrah Eunkyung Kim†	Seoul National University of Science and Technology	kr	Characteristics of Ti Nano Passivation for Low Temperature Cu Bonding
P2-05		Hung-Che Liu, Chih Chen†	National Yang Ming Chiao Tung University	tw	Voids Evolution in Cu-Cu Joints
P2-06		Jung Jaewoong, Ryu Jongin†	Korea Electronics Technology Institute	kr	Analysis and Comparison about Dielectric and Plating Conditions
P2-07		Haneul Han, Jinhyun Lee, Bongyoung Yoo†	Hanyang university	kr	A Study on the Electrodeposition of Copper at Low Temperature and its Application
P2-08		Sung Min Jeon, Sang-Yeob Kim, Su-Hun lee, Hyun-Jun Park, , Bae-yun Ah, Mong-hyun Cho, Jeong-Tak Moon†	MK Electron co., Ltd	kr	A Study on Au Coated High-Purity Silver-core Wire with Low Resistivity Bonded Possible in the Atmosphere
P2-09		SukYoun Lee, JeongTak Moon†, MongHyun Cho, GyuMin Sim, HyunJun Park	MK Electron co., Ltd	kr	New Metal Coated Cu Bonding Wire for Semiconductor Packaging
P2-10		Byeongjin Ahn, Jahyeon Kim, Gyeong-Yeong Cheon, Jungsoo Kim, Chang-Woo Lee, Young-Bae Park*, Yong-Ho Ko†	Korea Institute of Industrial Technology, Andong National University*	kr	Joint Reliabilities of Al Wire Bonding on Cu(OSP) and ENIG Surface-finished Substrate under Complexed Stress with Current and Temperature
P2-11		Woobin Kwon, Youn-Hye Kim*, Yohei Kotsugi*,**, Kirak Son***, Soo-Hyun Kim*, Young-Bae Park†	Andong National University, Yeungnam University*, Tanaka precious metals**, Electronics and Telecommunications Research Institute***	kr	Interfacial Adhesion Energy of TiN Diffusion Barriers Prepared by Atomic Layer Deposition for Ru Interconnect
P2-12		Yoon Hwan Moon*, Yong Sung Eom†, Jiho Joo, Gwang Mun Choi, Ki seok Jang, In Seok Kye, Chanmi Lee, Yong Jun Oh*, Kwang Seong Choi	Hanbat National University*, Electronics and Telecommunications Research Institute	kr	Analysis of Bonding Structure of Flexible Devices Using Anisotropic Solder Paste (ASP) and Laser-Assisted Bonding (LAB) Technology
P2-13		Ki-Seok Jang, Yong-Sung Eom†, Gwang-Mun Choi, Kook-Man Kim*, Jeong-Soo Lee*, Jiho Joo, Chan-Mi Lee, Ho-Gyeong Yun, In-Seok Kye, Bong-Sun Yoo*, Kwang-Seong Choi	Electronics and Telecommunications Research Institute, BNF Corporation*	kr	Laser Assisted Bonding Process Using with Anistropic Solder Paste(ASP) for Fine-Pitch Interconnection
P2-14		Duc Thinh Vuong, Xuan Luc Le, Sung-Hoon Choa†	Seoul National University of Science and Technology	kr	Fatigue Life Prediction for Solder Joint of Flip-chip in Laser Bonding Process by Numerical Analysis
P2-15		Dong Hwan Lee, Min Seong Jeong, Jeong Won Yoon†	Chungbuk National University	kr	Comparative Study of Laser and Reflow Soldered Sn-3.0Ag-0.5Cu/OSP Joints

P2-16		Kyung-Yeol Kim, Eun Ha, Kyung Deuk Min, Haksan Jeong, Seung-Boo Jung†	Sungkyunkwan University	kr	The Transient Liquid Phase Bonding by Ultrasonic-assisted Soldering of Cu Contained Sn-58Bi Solder Paste for High-Temperature Packaging Applications
P2-17		Chen Shiqi†, Gan Guisheng	Chongqing University of Technology	cn	Effect of Rapid Thermal Shock Cycle on the Thermomechanical Reliability of Sn-90Pb Solder Bumps
P2-18		Jahyeon Kim, Nayoung We, Byeongjin An, Gyeongyeong Cheon, Dongyurl Yu, Sehoon Yoo, Young-Bae Park*, Yong-Ho Ko†	Korea Institute of Industrial Technology, Andong National University*	kr	Evaluations on Interfacial Reactions and Mechanical Properties of Hybrid Solder Joints with Low-temperature and Mid-temperature Pb-free Solders
P2-19		Hoekyung Kim†, Young-Min Im	Korea Electronics Technology Institute	kr	A Fixed Folding Test Method for Measuring Durability of Flexible Opto-Electric Circuit Cables
P2-20		Junho Lee, Kyu-bong Jang*, Sihyun Lee, Seoah Kim, Sungwook Mhin†	Kyonggi University, Inha University*	kr	The Effect of MgO and Sintering Temperature on Mechanical Properties of MgO-ZrO_2-TiC Composite
P2-21		Minjeong Sohn, Byeongjin Ahn, Yong-Ho Ko, Byeong-Kwon Ju, Tae-Ik Lee†	Korea Institute of Industrial Technology	kr	Evaluating Thermal Deformation of Solder Joint in Electronic Packages
P2-22		SoYeon Jun, Junhyuk Yu, HyeonJoo Yoo, Sehoon Yoo†	Korea Institute of Industrial Technology	kr	Solderability of Water-Soluble Sn-3.0Ag-0.5Cu Solder Paste with Molecular Weight of Solvent
P2-23		Tae-Young Lee, So-Yeon Jun, Young-Ho Kim, Sehoon Yoo†	Korea Institute of Industrial Technology	kr	Novel Nickel-free Electroless Palladium Immersion Gold (EPIG) Surface Finish for Fine Pitch Flip Chip Interconnects
P2-24		Yun-Chan Kim, Junghwan Bang†	Korea Institute of Industrial Technology	kr	The Study on Properties of Sintered Joint Using Silver Paste for High-temperature Operation
P2-25	PCB, Solder, & Assembly Process	Seol Yoo*,**, Ji Hun Park**, Sang Hyuk Yoon**, Yoon Hwi Park**, Seung-Boo Jung†*	Sungkyunkwan University*, Korea Instrument Co., Ltd.**	kr	Influence of Solder Alloy Compositions on the Microstructure and the Mechanical Properties of MEMS Probe Solder Joints by Laser Soldering
P2-26		Nakyung Oh, Seong-Gyu Ko, Hyeon-Woo Son, Sang-Wook Kim, Soong-Keun Hyun†	Inha University	kr	Evaluation of the Bonding Properties of Bi-Te Thermoelectric Element and Porous Cu Electrode Using SAC305 Solder
P2-27		Sri Harini Rajendran, Do Hoon Cho, Seong Min Seo, Jae Pil Jung†	University of seoul	in	Adapting Nanocomposite Micro-solder Ball Process to Next-gen Advanced Packaging
P2-28		Jaeyeol Son, Seulgi Lee*, Youngwoo Lee*, Haksan Jeong, SeungBoo Jung†	Sungkyunkwan University, MK Electron Co.,Ltd.*	kr	Study of Solder Composition for High TC Reliability as Optimized Ag and Bi Contents for Advanced BGA PKG with Cu-OSP Pad Finish.
P2-29		Seo-Hyang LEE, Yong-Suk KIM, Jae-Ho LEE†	Hongik University	kr	Electrochemical Evaluation of PCB Copper Etchant to Reduce Undercut Etching
P2-30		Haksan Jeong, Kyung-Yeol Kim, Kyung Deuk Min, Seung-Boo Jung†	Sungkyunkwan University	kr	Mechanical Reliability of Cu Core Solder Joints after Electromigration
P2-31		MinSeong Jeong, DongHwan Lee, HyeonTae Kim, YoungJin Seo, MinHaeng Heo, JeongWon Yoon†	Chungbuk National University	kr	Mechanical Behavior and Shear Property of Lead-free Solder Joints at Elevated Temperatures
P2-32		Yun-Ju Cho, Sang-Yeob Kim, Mong-Hyun Cho, Jung-Tak Moon†	MK Electron Co.,Ltd.	kr	Comparison of Sintering Properties according to Powder Particle Size and Flux Composition
P2-33		KyuBong Yeon†*, DuHo Lee	Korea Automotive Technology Institute	kr	Electromagnetic Field Analysis for ROA (Rear Occupant Alert) Sensor Packaging Utilizing 60 GHz Band Millimeter Wave
P2-34		KyuBong Yeon†*, DuHo Lee	Korea Automotive Technology Institute	kr	A Study on the PRUL (Prognostics of Remaining Useful Life) Sensor Packaging for Automotive Self-diagnostics
P2-35		KyuBong Yeon†*, DuHo Lee	Korea Automotive Technology Institute	kr	A Study on Fault Injection Test Method of System on Chip Packaging for ASIL (Automotive Safety Integrity Level)
P2-36		KyuBong Yeon†*, DuHo Lee	Korea Automotive Technology Institute	kr	A Study on the Dependability Characteristics of Time Driven Network in System on Chip Packaging for Autonomous Vehicle Valet Parking
P2-37	Automotive & Power Electronic Packaging	Kirak Son, Aesun Oh, Eunyoung Park, Kyu Ho Yeon*, Bum-Gyu Baek*, Hyun-Cheol Bae†	Electronics and Telecommunications Research Institute, KD MTEC*	kr	Effect of Sintering Process on the Interfacial Reliability of Micro-nano Bimodal Cu Sintered Joints on Power Electronics Substrate
P2-38		Woo Lim Choi, Jong-Hyun Lee†	Seoul National University of Science and Technology	kr	Low-Temperature in Situ Formation of Submicrometer Cu Particles by Pyrolysis of Cu Formate Complex and Sinter-Bonding Properties for Cu-Cu Die-Attachment
P2-39		Young-Jung Kim, Jong-Hyun Lee†	Seoul National University of Science and Technology	kr	Short Pressure-Assisted Sinter Bonding Using Paste Containing Fractal Micron Ag Particles and Effect of Subsequent Pressureless Annealing on Joint Strength
P2-40		Dongjin Kim†*,**, Chuantong Chen**, Katsuaki Suganuma**, Min-Su Kim*, Yong-Ho Ko*, Sehoon Yoo*	Korea Institute of Industrial Technology*, Osaka University**	kr	On-line Thermal Resistance and Power Cycle Test Monitoring for EV Power Modules With Ag Sinter Joining and Pb, Pb-Free Solders by SiC TEG Chip
P2-41		Jong-Min Jeong, Jungsoo Kim, Seung-Boo Jung, Min-Su Kim†	Korea Institute of Industrial Technology	kr	Effect of Electroplated Ni Finish on Interfacial Reaction and Mechanical Property of Al/Cu Ultrasonic Welding Joint
P2-42		Kyung Deuk Min, Jun-Ho Jang, Haksan Jeong, DongGil Kang, Seung-Boo Jung†	Sungkyunkwan University	kr	Predicting the Mechanical, Creep Properties of BGA Solder Joints Through Nanoindentation
P2-43		Min Kyu Kang†	Graduate School of Convergence Science and Technology Seoul National University	kr	Analysis of Influencing Factors of Package Strength Using FEM Simulation
P2-44	Reliability of Electronic Devices & Systems	Dohoen Kim, Gahui Kim, Hyejin Kim, Seunghyan Kim, Dongik Jeong, Young-Bae Park†	Andong National univaersity	kr	Effect of Dielectric Curing Condition on the Interfacial Adhesion Energies of Photosensitive Polyimide Capping Layer/ Cu Layer for Fan-out Package
P2-45		Wonjoo Lee, Jae Hun Kim, Suhan Kim, Seohyun Jang, Hyunseong Shin†, YeongKook Kim†	Inha University	kr	Temporal Homogenization Formulation of Viscoelastic Materials Subjected to the Cyclic Vibration
P2-46		Amin Khaliq, Myung Yung Jeong†	Pusan National University	kr	Stress Analysis of Cylindrical Adhesive Lap Joint between Nickel and CFRP